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#### **ABSTRACT OF THE DISCLOSURE**

A process of dual damascene or damascene. The dual damascene process comprises providing an etching apparatus, a DCM machine and a wafer, the wafer having a metal line, a stop  
5 layer, a dielectric layer, a contact, and a photoresist layer. The dielectric layer and the contact are etched in the etching apparatus to form a trench. The photoresist and the contact are ashed in the DCM machine. Finally the wafer is wet cleaned.